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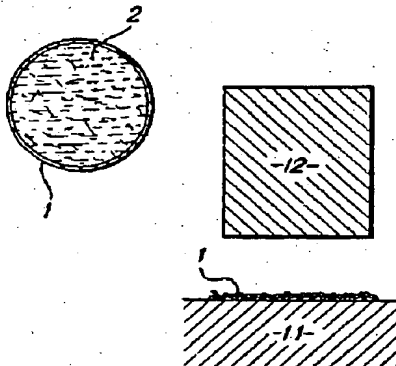
**(54) CAPSULE TYPE ADHESIVE AND BONDING
PROCESS USING SAME**

(57) Abstract:

PURPOSE: To accomplish bonding in good workability along with economy and clearness, by putting a capsule-type adhesive with an adhesive encapsulated in capsules between objects followed by pressing said objects to collapse the capsules.

CONSTITUTION: For example, a capsule type adhesive with an adhesive 2 encapsulated in spherical capsules 1 with a size $1W5\mu m$ is put between objects 11 and 12 followed by pressing these objects to collapse said capsules 1, thus accomplishing the objective bonding.

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